| 発行整理番号 Issue NO. : | T1LC-05008 |
|-----------------------|------------------------|
| 発 行 日 | 2005年2月24日 |
| Date of Issue : | February 24,2005 |
| 発行区分 | ■ 新規 変更 更新 |
| Classification: | New □ Change □ Renewal |

<u>To Digi-Key</u>

納入仕様書 PRODUCT SPECIFICATION FOR INFORMATION

| 製品名称 Product Description | : High Frequency Filter | , |
|-----------------------------------|--|-------------------------------------|
| 製品品番 Product Part Number | : ELB2A009 | |
| 松 下 品 番 Matsushita Part Number | : ELB2A009 | |
| 適用(使用機種等) Applications | : Cordless phone | |
| | 上記以外の適用に際しては,事前に弊社 For other applications,contact | |
| 製 造 部 署 Manufactured by | : JAPAN | |
| 本仕様書の有効期間 Term of Validity | 発行日から : | まで有効とします。 from the date of issue |

お得意様ご使用欄 CUSTOMER USE ONLY

この書類を確かに受領しました。 This was certainly received by us.

松下電子部品株式会社 変成器ビジネスユニット

Matsushita Electronic Components Co.,Ltd. Power Supply and Inductive Products Business Unit

〒571-8506 大阪府 門真市 大字門真1006番地 1006 Kadoma, Kadoma City, Osaka 571-8506, Japan

電話(代表) (06) 6908-3191 Tel (06) 6908-3191 (Representative)

| コイル技術グループ | | | | |
|---------------|----------------|-----------------|--|--|
| Inductive Eng | ineering Group | | | |
| | Te Fa | x (06)6908-7307 | | |
| 責任者 | 検印 | 担当者 | | |
| Approved | Checked | Designed | | |
| 914WWWWW RD | | MShiba | | |

発行部署名 Prepared by

1. この製品の使用材料は、「化学物質の審査及び製造等の規制に関する法律」 に基き、すべて既存化学物質として記載されている材料です。

All the materials used in this product are registered material under the Law Concerning the Examination and Regulation of Manufacture, etc. of Chemical Substances.

2. 本製品は、モントリオール議定書で規制されているオゾン層破壊物質(ODC) を製造工程及び購入部品・材料で一切使用していません。

This product has not been manufactured with any ozone depleting chemical controlled under the Montreal Protocol.

3. この製品に使用している全ての材料には、臭素系特定難燃物質「PBBOs、 PBBs」を含有しておりません。

All the materials used in this product contain no brominated materials of PBBOs or PBBs as the flame-retardant.

 納入仕様書の「有効期間」について 有効期間は、特に、申し出のない限り(お客様の要望を含み)自動更新とします。
その際、連絡書・仕様書は、発行致しません。

"The Term of Validity" of Product Specifications for Information Unless otherwise requested (including from customer), the term of validity shall be renewed automatically.

Then, informations and specifications shall be not issued.

| | | | | | | (3-14) |
|-----|----------------|--------------|-----------------|--------|------------------------|-----------------|
| | | SPECIFICATIO | ONS (Record | d of R | evision) | |
| Сι | ustomer's Code | ELB2A009 | Company name | Mats | ushita Electronic Comp | onents Co.,Ltd. |
| М | atsushita Code | ELB2A009 | Publisher | Mats | ushita Electronic Comp | onents Co.,Ltd. |
| No. | Date | Details o | f change | | Operation | Checked |
| 1 | Feb.25.2005 | Ň | €W | | After Receiving Spec. | 914000000000 |
| 2 | | | | | | |
| 3 | | | | | | |
| 4 | | | | | | |
| 5 | | | | | | |
| 6 | | | | | | |
| 7 | | | | | | |
| 8 | | | | | | |
| 9 | | | | | | |
| 10 | | | | | | |

| Classificatior | 1 | | | | Code No. | (4 - 14 (P C |
|----------------|--|---|-----------------|-------------|----------|-----------------|
| | | SPECIFICATION | IS a | | | (R 0 -05008 |
| Name | High-Frequency Bandpass Filter | | | 1 - 1 | | |
| 1.SCOPI | | | | | | |
| | This specification cove to | ers the High-Frequency Bandpa Digi-Key | ass Filter to b | e delivered | | |
| 2.PARTN | | products in this specification | shall be | | | |
| | | ELB2A009 | | | | |
| 3.INDIVI | DUAL | Code No. | 151- | ELB2A009 | (R0) | - |
| | (1)APPEARANCE&DIN As specified in | /IENSIONS the appearance & dimensions. | | | | |
| | | AND METAL MASK DETAIL the mounting detail and metal | mask detail. | | | |
| | (3)ELECTRICAL CHAP As specified in | RACTERISTICS the electrical characteristics. | | | | |
| | (4)PERFORMANCE C As specified in | HARACTERISTICS the freq. response & group del | ay. | | | |
| 4.COMM | ON | Code No. | 151- | LC2A005 | (R0) | - |
| | (1)RELIABILITY CHAF As specified in | ACTERISTICS the reliability characteristics. | | | | |
| | (2)ATTENTION As specified in | the attention. | | | | |
| | (3)TEST METHOD As specified in | the test method. | | | | |
| | (4)CONSRRUCTION As specified in | the construction. | | | | |
| | (5)PACKAGE As specified in | the package. | | | | |
| 5.REMA | (1)PRODUCING DIST | RICT dule DC Matsushita Electronic | Components | Co.,Ltd. | | |
| | | o-Cho Ibi-Gun Gifu PREF,501 | | | | |
| lo. Date | | Revision | Checke | dDate | Feb.2 | 5.2005 |
| | | | | Approval | Checked | Design |
| | · · · · · · · · · · · · · · · · · · · | | | 10 | | |

-





Classification

SPECIFICATION(COMMON)

Code No. (R0) 151-LC2A005

Subject

High-Frequency Bandpass Filter Reliability Characteristics

1 - 8

| Moisture The electrical Filters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±8h. Moisture characteristic shall be Measurements shall be made after 48h stabilization at room temperature. Resistance as shown in Table of individual specification Filters shall be subjected to 85°C±2°C for 500h±8h. Filters shall be subjected to 85°C±2°C for 500h±8h. Filters shall be subjected to 85°C±2°C for 500h±8h. | | Items | Specification | Toot Mothod/Condition |
|---|----------|-----------------|--|--|
| Molisture Resistance Characteristic shall be as shown in Table of individual specification Measurements shall be subjected to 85°C±2°C for 500h±8h. Measurements shall be made after 48h stabilization at room temperature. Cold Resistance Cold Resistance Filters shall be subjected to 40°C±2°C for 500h±8h. Measurements shall be made after 48h stabilization at room temperature. Thermal Characteristic Filters shall be subjected to repeat 100 times to the following temperature cycle. Thermal Characteristic Filters shall be subjected to 70°C±2°C 30 min 2. Moisture Life Thermal Characteristic Moisture Life The electrical Heart Resistance Thermal Life The electrical Heart Resistance Heart Resistance The electrical Heart Resistance Heart Resistance The electrical Heart Resistance Vibration Resistance The terminals shall be not abnormality. Resistance Heart Resistance The terminals shall be not abnormality. The ter | | Rems | | Test Method/Condition Filters shall be subjected to $90\% \sim 95\%$ BH at $60\% + 2\%$ for $500b+8b$ |
| Resistance as shown in Table of individual specification Thermal Resistance Filters shall be subjected to 45°C±2°C for 500h±8h. Measurements shall be made after 48h stabilization at room temperature. Filters shall be subjected to 40°C±2°C for 500h±8h. Measurements shall be made after 48h stabilization at room temperature. Filters shall be subjected to repeat 100 times to the following temperature cycle. Thermal Impact Thermal Characteristic Thermal Characteristic Filters shall be subjected to repeat 100 times to the following temperature cycle. Thermal Life Thermal Characteristic Filters shall be subjected to repeat 100 times to the following temperature cycle. Thermal Life Thermal Characteristic Filters shall be subjected to repeat 100 times to the following temperature cycle. Checked at any temperature from -20°C±3°C to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 485°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 480°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization, repeat 2 times. Heart Resistance Filters shall be subjected to 48°C±2°C for 2±0°C for 5±0°C for 10±0±0.5s, and more than 2minutes stabilization, repeat 2 times. | | Moisture | | |
| Image: state of the subject | | | | |
| Thermal Resistance Filters shall be subjected to 35°C-22°C for 500hz8h. Measurements shall be made after 48h stabilization at room temperature. Cold Resistance Cold Resistance Filters shall be subjected to -40°C+2°C for 500hz8h. Measurements shall be made after 48h stabilization at room temperature. Thermal Impact Filters shall be subjected to repeat 100 times to the following temperature cycle. Thermal Impact Checked at any temperature form -20°C±3°C to 85°C±3°C. (Standard at 2°C) Moisture Life The electrical torm temperature. Moisture Life Thermal Life The electrical Heart Resistance Thermal Life The electrical torm temperature. Measurements shall be subjected to 80% -95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s as shown in Table of Apoperance and structure shall be no abnormality. Filters shall be no abnormality. Filters shall be subjected to dipping in solder for 10s±0.5s. Individual specification Apoperance and structure shall be no abnormality. Fall on a hard wcoden board from a height of 1.0m 10 times. Fall on a hard wcoden board from a height of 1.0m 10 times. Fall on a hard w | | | | |
| Thermal Resistance Measurements shall be made after 48h stabilization at room temperature. Cold Resistance Cold Resistance Filters shall be subjected to -40°C±2°C for 500h±8h. Measurements shall be made after 48h stabilization at room temperature. Thermal Impact Filters shall be subjected to repeat 100 times to the following temperature cycle. 1,-40°C±2°C 30 min , 2, 85°C±2°C 30 min Measurements shall be made after 48h bour stabilization at room temperature. Checked at any temperature from -20°C±3°C to 35°C±3°C. (standard at 20°C) Thermal Life Filters shall be subjected to 90%-05%RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Pitters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Retire Solder Heart Resistance The electrical characteristic shall be subjected to dipping in solder at 270°C±5°C for 5± ±0.5s. individual specification Appearance and surcure shall be made after 48h stabilization, repeat 2 times. Vibration Resistance Filters shall be subjected to dipping in solder at 270°C±5°C for 10±0.5s. individual specification Appearance and surcure shall be made after 48h stabilization, repeat 2 times. Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance The terminals shall be at | | | ······································ | |
| Status Filters shall be subjected to -40°C±2°C for 500h±8h. Measurements shall be made after 48h stabilization at room temperature. Thermal Impact Filters shall be subjected to repeat 100 times to the following temperature cycle. 1.40°C±2°C 30 min .2.85°±2°C 30 min Measurements shall be made after 48h stabilization at room temperature from -20°C±3°C to 85°±2°C for 500h±2h. With DC 15V loaded between the terminals. Measurements shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to dipping in solder at 270°C±5°C for 5± ±0.5s abnormality. Filters shall be subjected to dipping in solder at 270°C±5°C for 5± ±0.5s abnormality. Filters shall be nade after 48h stabilization, repeat 2 times. The electrical Appearance and abnormality. Filters shall be aubjected to dipping in solder at 270°C±5°C for 10±0.5s. abnormality. Fall on a hard wooden board from a height of 1.0m 10 times. Fesistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Filters and 55 Hz, an amplitude of 1.5mm for 2h in each of 3 mutually perpencicular | | Thermal | | Measurements shall be made after 48h stabilization at room temperature. |
| Cold Measurements shall be made after 48h stabilization at room temperature. Thermal Impact Filters shall be subjected to repeat 100 times to the following temperature cycle. Thermal Characteristic 1.40°C ±2°C 30 min , 2.8°C ±2°C 00 min Measurements shall be made after 48h stabilization at room temperature. Moisture Life Checked at any temperature from -20°C ±3°C to 85°C ±2°C of 500h±2h with DC 15V loaded between the terminals. Measurements shall be subjected to 85°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermal Life Filters shall be subjected to 85°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 85°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 85°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to dipping in solder at 270°C ±5°C for 5s ±0.5s. Resistance Filters shall be subjected to 10mm ^15mm from attachment surface. Resistance Appearance and structure shall be no a for 10s±0.5s. and more than 2minutes stabilization, repeat 2 times. Nibration Presistance Fall on a hard wooden board from a height of 1.0m 10 times. Pessistance Vibrating at the | | Resistance | | |
| Cold Resistance Thermal Impact Filters shall be subjected to repeat 100 times to the following temperature cycle. Thermal Impact 1.40°C ±2°C 30 min , 2.5°C ±2°C 00 min Measurements shall be made after 48 hour stabilization at room temperature. Thermal Characteristic Chacked at any temperature from .20°C ±3°C to 85°C ±3°C. (standard at 20°C) Moisture Life Filters shall be subjected to 90% ~95% RH at 60°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermal Life Filters shall be subjected to 85°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 85°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 85°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Filters shall be subjected to 85°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be nade after 48h stabilization at room conditions. Filters shall be subjected to 85°C ±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be nade after 48h stabilization at room conditions. Resistance Filters shall be subjected to 85°C ±2°C for 10±0.5s. Imperatione foo 1.0mm ^15mm from attachment surface. | | | | |
| Pesistance Filters shall be subjected to repeat 100 times to the following temperature cycle. Thermal Impact 1.40C22C30 min, 2.85C±2C 30 min Measurements shall be made after 48 hour stabilization at room temperature. Checked at any temperature from -20°C±3°C to 85°C±2°C to 500h±2h with DC 15°C loaded between the terminals. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15°C loaded between the terminals. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15°C loaded between the terminals. Measurements shall be subjected to 85°C±2°C for 500h±2h with DC 15°C loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Pilters shall be subjected to 65°C±2°C for 500h±2h with DC 15°C loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Pilters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~ 1.5mm from attachment surface. Pilters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~ 1.5mm from attachment surface. Reflow Solder Filters shall be no at a filter dipping in solder at 270°C±5°C for 10s±0.5s. Impact Filters and wooden board from a height of 1.0m 10 times. Resistance Vibration Piseting Fall on a hard wooden board from a height of 1.0m 10 times. Solderability The terminals shall be solder at 230°C± | | | | |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermai Life The electrical Dipping Solder The electrical characteristic shall be as shown in Table of the subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Felow Solder Heart Resistance Impact Reflow Solder Heart Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | 8 | | | Measurements shall be made after 48h stabilization at room temperature. |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermal Life The electrical Dipping Solder The electrical characteristic shall be of levements shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Filters shall be no Heart Appearance and structure shall be no Impact Structure shall be no Bending Structure shall be no Vibration Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | stic | Resistance | | |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermai Life The electrical Dipping Solder The electrical characteristic shall be as shown in Table of the subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Felow Solder Heart Resistance Impact Reflow Solder Heart Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | teri | | | |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermal Life The electrical Dipping Solder The electrical characteristic shall be of levements shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Filters shall be no Heart Appearance and structure shall be no Impact Structure shall be no Bending Structure shall be no Vibration Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | rac | | | |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermal Life The electrical Dipping Solder The electrical characteristic shall be of levements shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Filters shall be no Heart Appearance and structure shall be no Impact Structure shall be no Bending Structure shall be no Vibration Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | ha | Thormal Impact | | |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermal Life The electrical Dipping Solder The electrical characteristic shall be of levements shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Filters shall be no Heart Appearance and structure shall be no Impact Structure shall be no Bending Structure shall be no Vibration Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | | i mermar impaci | | |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Pipping Solder The electrical characteristic shall be as shown in Table of nesistance Resistance Filters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Reflow Solder Heart Resistance Heart Resistance Filters shall be no abnormality. for 10±10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10±0.5s. Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | nta | | | |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermal Life The electrical Dipping Solder The electrical characteristic shall be of levements shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Filters shall be no Heart Appearance and structure shall be no Impact Structure shall be no Bending Structure shall be no Vibration Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | це Д | | | Checked at any temperature from $-20^{\circ}C+3^{\circ}C$ to $85^{\circ}C+3^{\circ}C$ |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermal Life The electrical Dipping Solder The electrical characteristic shall be of levements shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Filters shall be no Heart Appearance and structure shall be no Impact Structure shall be no Bending Structure shall be no Vibration Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | l 0 | | | |
| Pilters shall be subjected to 90% ~95% RH at 60°C±2°C for 500h±2h with DC 15V loaded between the terminals. Moisture Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Pipping Solder The electrical characteristic shall be as shown in Table of nesistance Resistance Filters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Reflow Solder Heart Resistance Heart Resistance Filters shall be no abnormality. for 10±10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10±0.5s. Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C | l ž | Characteristic | | |
| Moisture Life With DC 15V loaded between the terminals. Moisture Life Thermal Life Thermal Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Dipping Solder The electrical characteristic shall be as shown in Table of individual specification Appearance and Appearance and Structure shall be no abnormality. Refitow Solder Filters shall be normality. Heart Resistance Vibration Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration at least 90% covered with solder. Bending The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating -20°C ~85°C After dipping in solder at 230°C±5°C for 2s±0.5s. | Π | | | Filters shall be subjected to 90% \sim 95% RH at 60°C+2°C for 500h+2h |
| Moisture Life Measurements shall be made after 48h stabilization at room conditions. Thermal Life Filters shall be subjected to 85°C±2°C for 500h±2h with DC 15V loaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Thermal Life The electrical characteristic shall be as shown in Table of nearcateristic shall be of individual specification Appearance and structure shall be no abnormality. Filters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Heart Resistance Filters shall be no abnormality. Filters shall be made after dipping in solder at 270°C±5°C for 5s ±0.5s to 10s±0.5s. Impact Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. Operating temp. range -20°C ~85°C Operating temp. range -20°C ~85°C | | | | |
| Image: Thermal Life Ibaded between the terminals. Measurements shall be made after 48h stabilization at room conditions. Dipping Solder Heart Resistance The electrical characteristic shall be as shown in Table of individual specification Appearance and structure shall be n abnormality. Filters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Heart Resistance Filters shall be n abnormality. To 10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10s±0.5s , and more than 2minutes stabilization, repeat 2 times. Vibration Resistance Impact Heasistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range The terminals shall be at least 90% covered After dipping in solder at 230°C±5°C for 2s±0.5s. | | Moisture Life | | |
| Image: Product of the state in the state | | | | |
| Image: Product of the stability of the s | | | | |
| Impact Resistance The electrical characteristic shall be as shown in Table of individual specification Appearance and structure shall be no abnormality. Filters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Impact Resistance The electrical characteristic shall be of abnormality. Filters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Impact Resistance Filters shall be no abnormality. Filters shall be made after dipping in solder for 10s±0.5s. Vibration Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range '20°C~85°C After dipping in solder at 230°C±5°C for 2s±0.5s. | | | | |
| Upping Solder Heart Resistance The electrical characteristic shall be as shown in Table of individual specification Appearance and structure shall be no abnormality. Filters shall be subjected to dipping in solder at 270°C±5°C for 5s ±0.5s up to 1.0mm ~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Heart Resistance Appearance and structure shall be no abnormality. 150±10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10s±0.5s, and more than 2minutes stabilization, repeat 2 times. Impact Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C ~85°C After dipping in solder at 230°C±5°C for 2s±0.5s. | | | | |
| Dipping Solder Heart Resistance characteristic shall be as shown in Table of individual specification Appearance and structure shall be no abnormality. up to 1.0mm~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Heart Resistance Reflow Solder Heart Resistance 150±10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10s±0.5s , and more than 2minutes stabilization, repeat 2 times. Impact Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C~85°C After dipping in solder at 230°C±5°C for 2s±0.5s. | | I hermal Life | | Measurements shall be made after 48h stabilization at room conditions. |
| Dipping Solder Heart Resistance characteristic shall be as shown in Table of individual specification Appearance and structure shall be no abnormality. up to 1.0mm~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Heart Resistance Reflow Solder Heart Resistance 150±10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10s±0.5s , and more than 2minutes stabilization, repeat 2 times. Impact Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C~85°C After dipping in solder at 230°C±5°C for 2s±0.5s. | | | | |
| Dipping Solder Heart Resistance characteristic shall be as shown in Table of individual specification Appearance and structure shall be no abnormality. up to 1.0mm~1.5mm from attachment surface. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Heart Resistance Reflow Solder Heart Resistance 150±10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10s±0.5s , and more than 2minutes stabilization, repeat 2 times. Impact Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C~85°C After dipping in solder at 230°C±5°C for 2s±0.5s. | <u> </u> | | The electrical | Eiltern shall be subjected to disping in colder at 270% $\pm 5\%$ for Eq. (0.55) |
| Heart Resistance as shown in Table of Individual specification Appearance and structure shall be no abnormality. Measurements shall be made after dipping in solder for 10s±0.5s. Reflow Solder Heart Resistance Reflow Solder Heart Resistance Iso±10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10s±0.5s, and more than 2minutes stabilization, repeat 2 times. Vibration Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C~85°C After dipping in solder at 230°C±5°C for 2s±0.5s. | | Dipping Solder | | |
| Resistance Individual specification Appearance and structure shall be no abnormality. Individual specification Appearance and structure shall be no abnormality. 150±10°C preheat cycle for 2 minutes and through reflow at 230°C±5°C for 10s±0.5s ,and more than 2minutes stabilization, repeat 2 times. Impact Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C ~ 85°C -20°C ~ 85°C | | | | |
| Appearance and structure shall be no abnormality. 150±10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10s±0.5s , and more than 2minutes stabilization, repeat 2 times. Impact Resistance Impact Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Bending Strength The terminals shall be at least 90% covered with solder. Operating temp. range The terminals shall be at least 90% covered with solder. | | | | |
| Reflow Solder Heart Resistance structure shall be no abnormality. 150±10°C preheat cycle for 2 minutes, and through reflow at 230°C±5°C for 10s±0.5s , and more than 2minutes stabilization, repeat 2 times. Impact Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.5mm for 2h in each of 3 mutually perpendicular directions. Bending Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C~85°C -20°C~85°C | | riceletaries | | |
| Reflow Solder Heart Resistance abnormality. for 10s±0.5s ,and more than 2minutes stabilization, repeat 2 times. Impact Resistance Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Bending Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C ~85°C -20°C ~85°C | | | | 150±10℃ preheat cycle for 2 minutes and through reflow at 230℃±5℃ |
| Heart Resistance Heart Resistance Impact Resistance Impact Resistance Vibration Resistance Vibrating at the frequency varying uniformly between the approximate limit of 10Hz and 55 Hz, an amplitude of 1.5mm for 2h in each of 3 mutually perpendicular directions. Bending Strength The terminals shall be at least 90% covered with solder. Operating temp. range -20°C~85°C | | Reflow Solder | abnormality. | |
| Impact Resistance Fall on a hard wooden board from a height of 1.0m 10 times. Vibration Resistance Vibration Resistance Bending Strength Bending Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C~85°C | | Heart | , | |
| Nimpact Resistance Vibration Resistance Vibration Resistance Bending Strength Strength The terminals shall be at least 90% covered with solder. Operating temp. range -20°C~85°C | | Resistance | | |
| Nimpact Resistance Vibration Resistance Vibration Resistance Bending Strength Strength The terminals shall be at least 90% covered with solder. Operating temp. range -20°C~85°C | | | | |
| Operating temp. range -20°C~85°C Operating temp. range -20°C~85°C | <u> </u> | Impact | | Fall on a hard wooden board from a height of 1.0m 10 times. |
| Operating temp. range -20°C~85°C Operating temp. range -20°C~85°C | anic | | | |
| Operating temp. range -20°C ~ 85°C | che | | | |
| Operating temp. range -20°C ~ 85°C | Σ Θ | Vibratian | | |
| Bending Strength Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Apply pressure to test Jig (Fig.2) mounted component until 2mm 5 times. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C~85°C | | | | |
| Strength The terminals shall be at least 90% covered with solder. After dipping in solder at 230°C±5°C for 2s±0.5s. Operating temp. range -20°C~85°C | | nesisiance | | perpendicular directions. |
| Strength The terminals shall be at least 90% covered with solder. Solderability The terminals shall be at least 90% covered with solder. Operating temp. range -20°C~85°C | | | | Apply pressure to test, lig (Fig. 2) mounted component until 2mm E times |
| The terminals shall be at least 90% covered with solder. After dipping in solder at $230^{\circ}C \pm 5^{\circ}C$ for $2s \pm 0.5s$. Operating temp. range $-20^{\circ}C \sim 85^{\circ}C$ | | | | mpping pressure to test org (rig.2) mounted component until 2mm 5 times. |
| Solderabilityat least 90% covered with solder.Operating temp. range $-20^{\circ}C \sim 85^{\circ}C$ | | Strength | | |
| Solderabilityat least 90% covered with solder.Operating temp. range $-20^{\circ}C \sim 85^{\circ}C$ | | | The terminals shall be | After dipping in solder at 230°C±5°C for 2s±0.5s. |
| Solderability with solder. Operating temp. range -20°C~85°C | | | | |
| Operating temp. range | | Solderability | | |
| temp. range | | - | | |
| temp. range | | | | |
| temp. range | | Operating | -20℃~85℃ | · · · · · · · · · · · · · · · · · · · |
| | | | | |
| Failure rate 1.0FIT max. | | | | |
| | | Failure rate | 1.0FIT max. | |
| | | | | |







Material List

| No. | Code | Material |
|-----|------------------------|----------|
| 1 | Insulation materials A | Ceramic |
| 2 | Internal pattern | Ag |
| 3 | Insulation materials B | Glass |
| 4 | | Ag |
| 5 | Terminal electrode | Ni |
| 6 | | Sn |

MATSUSHITA ELECTRONIC COMPONENTS CO., LTD.







